

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	31	@ad<"20011226" and ((circuit adj board) PCB)) and (second adj ((bond\$3 adj site) (contact adj pad) (solder ball)) same (finger bar (elongated adj member)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 13:25
L2	12	@ad<"20011226" and ((circuit adj board) PCB)) and (second adj ((bond\$3 adj site) (contact adj pad) (solder adj ball)) same (finger bar (elongated adj member)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 13:26
L3	2	"20020139578"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 14:30
S1	1	@pn="6300782"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 14:30
S2	1	@pn="6277660"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 08:58
S3	1	@pn="6870276"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 10:49
S4	5721	438/14,17,18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 09:15
S5	1418	438/14,17,18.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:31

S7	1420	257/784.ccls. and @ad<"20011226"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 10:45
S8	1	@pn="6228548"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 09:53
S9	212	@ad<"20011226" and solder and ((bond adj site) (contact adj pad)) and wick\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 10:46
S10	38	@ad<"20011226" and solder same ((bond adj site) (contact adj pad)) same wick\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:09
S11	1	@pn="5024372"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 10:49
S12	304	@ad<"20011226" and solder same ((bond adj site) (contact adj pad)) same wet\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:18
S13	11	@ad<"20011226" and solder same ((bond adj site) (contact adj pad)) same wet\$4 same elongated	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:21
S14	44	@ad<"20011226" and solder same ((bond adj site) (contact adj pad)) same wet\$4 same (bar, finger, tab)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:40

S15	859	438/14,17,18.ccor. and @ad<"20011226"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:31
S16	5	((flowable adj conductive adj material) solder) and ((bond adj site) (contact adj pad)) and wet\$4 and (bar finger tab (elongated adj member))).clm.	US-PGPUB	OR	ON	2005/07/27 11:41
S17	44	@ad<"20011226" and solder same ((bond adj site) (contact adj pad)) same wet\$4 same (bar finger tab	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/27 11:40
S18	5	((flowable adj conductive adj material) solder) and ((bond adj site) (contact adj pad)) and (wet\$4 wick\$4) and (bar finger tab (elongated adj member))).clm.	US-PGPUB	OR	ON	2005/07/27 11:43